

IN THE CLAIMS:

Please cancel claims 1-24 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 25-38 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-24. (Canceled)

Claim 25. (New) A method for encapsulating a light emitting diode, which comprises the steps of:

- a) placing a crystalline grains light-emitting diode chip into a pre-punched first lead frame;
- 5 b) electrically connecting the first lead frame and the crystalline grains light-emitting diode chip to a second lead frame;
- c) encapsulating the crystalline grains light-emitting diode chip in a photosensitive polymer, the encapsulating step including placing the first lead frame, the crystalline grains light-emitting diode chip, and the
10 second lead frame in a mold and injecting the photosensitive polymer into the mold;
- d) curing the photosensitive polymer at room temperature to form an encapsulated light emitting diode; and
- e) cutting, testing and packaging the encapsulated light emitting diode.

Claim 26. (New) The method according to claim 25, wherein the photosensitive polymer utilized in the encapsulating step c) includes an Oligomer and a Photoinitiator.

Claim 27. (New) The method according to claim 26, wherein the photosensitive polymer utilized in the encapsulating step c) includes at least one selected from the group consisting of between 0.1% and 20% of a Silane coupling agent, 0.01% and 15% of an ultraviolet absorber agent, and between 0.01% and 20% of a Hindered Amine Light Stabilizer.

Claim 28. (New) The method according to claim 25, wherein the photosensitive polymer utilized in the encapsulating step c) includes a reactive Monomer and a Photoinitiator.

Claim 29. (New) The method according to claim 28, wherein the photosensitive polymer utilized in the encapsulating step c) includes at least one selected from the group consisting of between 0.1% and 20% of a Silane coupling agent, 0.01% and 15% of an ultraviolet absorber agent, and between 0.01% and 20% of a Hindered Amine Light Stabilizer.

Claim 30. (New) The method according to claim 25, wherein the photosensitive polymer utilized in the encapsulating step c) includes a Oligomer, a reactive Monomer, and a Photoinitiator.

Claim 31. (New) The method according to claim 30, wherein the photosensitive polymer utilized in the encapsulating step c) includes at least one selected from the group consisting of between 0.1% and 20% of a Silane coupling agent, 0.01% and 15% of an ultraviolet absorber agent, and between 0.01% and 20% of a Hindered Amine Light Stabilizer.

Claim 32. (New) The method according to claim 25, wherein the photosensitive polymer utilized in the encapsulating step c) includes at least one selected from the group consisting of between 0.1% and 20% of a Silane coupling agent, 0.01% and 15% of an ultraviolet absorber agent, and between 0.01% and 20% of a Hindered Amine Light Stabilizer.

Claim 33. (New) The method according to claim 25, wherein the curing step d) includes exposing the photosensitive polymer to a visible light.

Claim 34. (New) The method according to claim 33, wherein the curing step d) the photosensitive polymer is exposed to the visible light for a period of time between 5 seconds and 10 seconds.

Claim 35. (New) The method according to claim 25, wherein the curing step d) includes exposing the photosensitive polymer to an ultraviolet light.

Claim 36. (New) The method according to claim 35, wherein the curing step d) the photosensitive polymer is exposed to the ultraviolet light for a period of time between 5 seconds and 10 seconds.

Claim 37. (New) The method according to claim 25, wherein the curing step d) includes exposing the photosensitive polymer to an electron beam.

Claim 38. (New) The method according to claim 37, wherein the curing step d) the photosensitive polymer is exposed to the electron beam for a period of time between 5 seconds and 10 seconds.